

**CLAIMS**

1. In a liquid crystal display (LCD) fabrication process,  
a method for cleaning a resin residue, the method comprising:  
forming an electrode layer;  
5 forming a resin residue overlying a first area of the  
electrode layer;  
introducing a gas mixture including ozone into water to  
create a moist ozone gas; and,  
wet ashing the resin residue overlying the first area of the  
10 electrode layer using the moist ozone gas.
2. The method of claim 1 further comprising:  
following the forming of an electrode layer, forming an  
interlayer film of resin overlying the electrode later;  
15 patterning the resin interlayer;  
forming a via to access the first area of the electrode  
layer; and,  
wherein forming a resin residue overlying a first area of  
the electrode layer includes forming a resin residue in response to  
20 forming the via.
3. The method of claim 1 wherein forming an  
interlayer film of resin overlying an electrode layer includes forming  
an interlayer film of resin having a thickness in the range of 100 to  
25 1000 Angstroms (Å).

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9. In a liquid crystal display (LCD) fabrication process, a method for repairing a resin interlayer surface, the method comprising:

- 5                   forming an interlayer film of resin with a surface;  
                  dry etching the surface of the resin interlayer;  
                  in response to dry etching, damaging the resin interlayer surface;  
                  introducing a gas mixture including ozone into water to  
10   create a moist ozone gas;  
                  wet ashing the resin interlayer surface using the moist ozone gas; and,  
                  in response to wet ashing the resin interlayer surface, repairing the damage caused by the dry etching.

- 15                   10. The method of claim 9 further comprising:  
                  prior to forming an interlayer film of resin, forming an underlying electrode layer;  
                  following the forming of the interlayer film of resin,  
20   patterning the resin interlayer; and,  
                  wherein dry etching the resin interlayer includes forming a via to access a first area of the electrode layer using a dry etching process.

11. The method of claim 9 wherein forming an interlayer film of resin includes forming an interlayer film of resin having a thickness in the range of 100 to 1000 Angstroms (Å).

5 12. The method of claim 9 wherein introducing a gas mixture including ozone into water to create a moist ozone gas includes introducing a gas mixture of approximately 10 % ozone by molecular weight (wt %).

10 13. The method of claim 12 wherein introducing a gas mixture including ozone into water to create a moist ozone gas includes heating the water to a temperature of approximately 90 degrees C.

15 14. The method of claim 9 further comprising:  
following wet ashing the resin interlayer surface using the moist ozone gas, depositing a metal layer overlying the resin interlayer surface and the first area of the electrode to form a pixel electrode.

20 15. The method of claim 14 wherein depositing a metal layer overlying the resin interlayer surface and the first area of the electrode to form a pixel electrode includes depositing a metal layer material selected from the group including indium tin oxide (ITO) and aluminum overlying molybdenum.

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16. The method of claim 9 wherein wet ashing the resin interlayer surface using the moist ozone gas includes etching the resin interlayer surface at a rate of 200 Å per minute.

5 17. The method of claim 9 wherein wet ashing the resin interlayer surface using the moist ozone gas includes etching the resin interlayer surface a thickness in the range of 100 to 500 Å.

10 18. The method of claim 9 wherein dry etching the surface of the resin interlayer includes dry etching with a plasma including CF<sub>4</sub> and O<sub>2</sub>.

15 19. In a liquid crystal display (LCD) fabrication process, a method for repairing a resin interlayer surface, the method comprising:

forming an electrode;  
forming an interlayer film of resin with a surface,  
overlying an electrode later;  
patterning the resin interlayer;  
20 dry etching the surface of the resin interlayer to form a  
via to a first area of the electrode;  
in response to dry etching, damaging the resin interlayer  
surface;  
introducing a gas mixture including ozone into water to  
25 create a moist ozone gas;

wet ashing the resin interlayer surface using the moist ozone gas;

in response to wet ashing the resin interlayer surface, repairing the damage caused by the dry etching; and,

5                   forming a pixel electrode overlying the first area of the electrode and the surface of the resin interlayer.

~~20.~~ In a liquid crystal display (LCD) fabrication process, a method for cleaning a resin residue, the method comprising:

10                   forming an electrode layer;  
                    forming an interlayer film of resin overlying the electrode later;

                    patterning the resin interlayer;  
                    forming a via to access the first area of the electrode  
15    layer;

                    in response to forming the via, forming a resin residue overlying the first area of the electrode;

                    introducing a gas mixture including ozone into water to create a moist ozone gas;

20                   wet ashing the resin residue overlying the first area of the electrode layer using the moist ozone gas; and,

                    forming a pixel electrode overlying the first area of the electrode.

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